



Physical Interfaces & Carriers Japan TC Chapter

Meeting Summary and Minutes

Japan Standards Summer Meeting 2021

August 5th 9:00-11:00 (JST)

via OVTCC

TC Chapter Announcements

Next TC Chapter Meeting

The next committee meeting is undecided. Separately, coordinate with the chair to determine the date and time of the committee meeting.

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Yasuhisa Ito (MURATA MACHINERY), Tsuyoshi Nagashima (Miraial Co., Ltd.), Daisuke Sado (DAIHEN Corporation)

SEMI Staff: Hirofumi Kanno

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
DAIFUKU	Suzuki	Tomoko	KOKUSAI ELECTRIC	Matsuda	Mitsuhiro
Acteon NEXT	Komatsu	Shoji	TOKYO SEIMITSU	Taniguchi	Naomune
Marubeni Plax	Igeta	Luke	Tokyo Electron Ltd.	Mashiro	Supika
Ckplas	min	liu chih	Sony Corporation	Gotoh	Hisashi
SINFONIA TECHNOLOGY	Suzuki	Atsushi	Hirata Corporation	Toyoda	Noriyoshi
DAIHEN	Sado	Daisuke	Shin-Etsu Polymer Co., Ltd.	Shida	Hiroyuki
MURATA MACHINERY	Ito	Yasuhisa			
Ckplas	Cheng	Justin	SEMI Japan	Kanno	Hirofumi

Table 2 Leadership Changes

None

Table 3 Committee Structure Changes

None

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
6750	Line-Item Revision to SEMI E181-0321 - SPECIFICATION FOR PANEL FOUP FOR PANEL LEVEL PACKAGING, SEMI E181.1-0321 - SPECIFICATION FOR PANEL FOUP FOR 510 mm – 515 mm PANEL SIZE and 12 SLOTS, SEMI E181.2-0321 - SPECIFICATION FOR PANEL FOUP FOR 510 mm – 515 mm PANEL SIZE and 6 SLOTS, SEMI E181.3-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS, and SEMI E181.4-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS	Passed as balloted
6751	Line-Item Revision to SEMI E181.3-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS	Passed as balloted
6752	Line-Item Revision to SEMI E181.4-0321 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS	Passed as balloted



#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Activities Approved by the GCS between meetings of the TC Chapter

None

Table 6 Authorized Activities

None

Table 7 Authorized Ballots

None

Table 8 SNARF(s) Granted a One-Year Extension

None

Table 9 SNARF(s) Abolished

None

Table 10 Standard(s) to receive Inactive Status

None

Table 11 New Action Items

None

Table 12 Previous Meeting Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
05102021-01	SEMI Japan Staff	Check TFOFs in 5.5, 5.6 and 5.7, 5.9, and request the TF leader to submit the report if it is clearly indicated in the Liaison destination. No Liaison Destination: <ul style="list-style-type: none">● Panel Level Packaging (PLP) Glass Carrier Task Force● Panel Level Packaging (PLP) Panel Task Force Update: Ask each Task Force leader to designate the Global PIC Committee as Liaison; ask them to revise their TFOFs to include it, and request that they designate Liaison when writing their SNARFs. If a SNARF already exists, the SNARF should be revised. (SEMI Staff) Open
20210118-3	Supika Mashiro (Tokyo Electron)	Discuss future actions for SEMI E92-0302E (Reapproved 0615) by the next meeting. → Done. The PIC Maintenance Task Force will work on the revision of E92, since it was found by Supika Mashiro (Tokyo Electron) that it needs maintenance. Closed

1 Welcome, Reminders, and Introductions

Yasuhisa Ito (MURATA MACHINERY) called the meeting to order at 9:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 1. RequiredElementNov2020Rev1-E&J-r1

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion: Approve the previous meeting
By / 2nd: Shoji Komatsu (Acteon NEXT) / Mitsuhiro Matsuda (KOKUSAI ELECTRIC)
Discussion: None
Vote: 14:0
Attachment: 2, PICmins04142021v1.0

3 Liaison Reports

3.1 *PIC North America TC Chapter*

No report

3.2 *SEMI Staff Report*

Hirofumi Kanno (SEMI) gave the SEMI Staff Report. Of note:

Attachment: 3. Staff Report July 2021_v1

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

4.1 Document # 6750 Document Title: Line Item Revision to SEMI E181- SPECIFICATION FOR PANEL FOUF FOR PANEL LEVEL PACKAGING, SEMI E181.1- SPECIFICATION FOR PANEL FOUF FOR 510 mm – 515 mm PANEL SIZE and 12 SLOTS, SEMI E181.2- SPECIFICATION FOR PANEL FOUF FOR 510 mm – 515 mm PANEL SIZE and 6 SLOTS, SEMI E181.3- SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS, and SEMI E181.4- SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS

- 4.1.1 Line Item 1 Extended flange area
- 4.1.2 Line Item 2 Expansion of Presence area
- 4.1.3 Line Item 3 Exclude “door seal” from y4
- 4.1.4 Line Item 4 z15 error correction

Attachment: 4, Ballot report 6750

4.2 Document # 6751 Document Title: Line Item Revision to SEMI E181.3 - SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS

- 4.2.1 Line Item 1 Expansion of conveyor rail tolerances
- 4.2.2 Line Item 2 Correct “y” number

Attachment: 5, Ballot report 6751

4.3 Document # 6752 Line Item Revision to SEMI E181.4- SPECIFICATION FOR PANEL FOUF FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS

- 4.3.1 Line Item 1 Expansion of conveyor rail tolerances

Attachment: 6, Ballot report 6752

From this point, the chair was changed from Yasuhisa Ito (MURATA MACHINERY) to Daisuke Sado (Daihen).

5 Subcommittee and Task Force Reports

5.1 300 mm Tape Frame PI&C TF

Taniguchi *Naomune* (Toyo Seimitsu) reported for the task force.

Attachment: 7, 20210805_300mm Tape Frame PIC TF_ActivityReports

5.2 Global PIC Standards Maintenance TF

There is a request to keep E92 as Current. However, E92 would need major revision to keep it as Current. Supika Mashiro (Tokyo Electron) volunteered to become the author under the Task Force. SNARF submission is expected sometime between this meeting and next meeting.

5.3 Japan Electron Microscopy Workflow liaison TF

The activity was reported as attached slides.

Attachment: 8, 210805_PIC TC_EMWF TF

5.4 Panel Level Packaging Panel FOUP TF

Shoji Komatsu (Acteon NEXT) reported for the task force.

Attachment: 9, Panel FOUP TF report_20210805

5.5 [Liaison: 3D Packaging & Integration JA TC Chapter] Panel Level Packaging Glass Carrier TF

No report

5.6 [Liaison: 3D Packaging & Integration NA TC Chapter] Panel Level Packaging Panel TF

No report

5.7 [Liaison: Silicon Wafer Japan TC Chapter] JA Shipping Box TF – No Activity

No report

5.8 [Liaison: Traceability] Panel Level Packaging (PLP) Glass Carrier ID Marking TF

No report

6 Old Business

6.1 Project Period Review – None

6.2 5 years review - None

6.3 Open Action Item

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05102021-01	SEMI Japan Staff	Check TFOFs in 5.5, 5.6 and 5.7, 5.9, and request the TF leader to submit the report if it is clearly indicated in the Liaison destination. No Liaison Destination:

Item #	Assigned to	Details
		<ul style="list-style-type: none"> Panel Level Packaging (PLP) Glass Carrier Task Force Panel Level Packaging (PLP) Panel Task Force Update: Ask each Task Force leader to designate the Global PIC Committee as Liaison; ask them to revise their TFOFs to include it, and request that they designate Liaison when writing their SNARFs. If a SNARF already exists, the SNARF should be revised. (SEMI Staff) Open
20210118-3	Supika Mashiro (Tokyo Electron)	Discuss future actions for SEMI E92-0302E (Reapproved 0615) by the next meeting. → Done. The PIC Maintenance Task Force will work on the revision of E92, since it was found by Supika Mashiro (Tokyo Electron) that it needs maintenance. Closed

7 New Business

7.1 Report of Ratification Ballots Result

No Disapproval Votes exist both R6688 and R6689.

- R6688 - New Standard: Specification for 300mm Tape Frame FOUP Load Port
- R6689 - New Standard: Specification for 300mm Tape Frame FOUP

7.2 Discussion on the technical reasons accompanying Disapprove Votes to the following ratification ballots if any.

There is no discussion.

Attachment: 10, R6688_Ballot Review_final

Attachment: 11, R6689_Ballot Review_final

8 Next Meeting and Adjournment

The next committee meeting is undecided. Separately, coordinate with the chair to determine the date and time of the committee meeting.

Adjournment: 11:00

Respectfully submitted by:

Hirofumi Kanno

Manager

SEMI Japan

Phone: +81.3.3222.5863

Email: hkanno@semi.org

Minutes tentatively approved by:

Tsuyoshi Nagashima (Miraial), Co-chair	<Date approved>
Daisuke Sado (Daihen), Co-chair	<Date approved>
Ito Yasuhisa (Murata Machinery), Co-chair	

Table 13 Index of Available Attachments^{#1}

Title	Title
1.RequiredElementNov2020Rev1-E&J-r1	2, PICmins04142021v1.0

Table 13 Index of Available Attachments^{#1}

3. Staff Report July 2021_v1	4, Ballot report 6750
5, Ballot report 6751	6, Ballot report 6752
7, 20210805_300mm Tape Frame PIC TF_ActivityReports	8, 210805_PIC TC_EMWF TF
9, Panel FOUP TF report_20210805	10, R6688_Ballot Review_final
11, R6689_Ballot Review_final	

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.